

S E R V I C E N O T E

SUPERSEDES: None

5DX Structural Process Test Systems Series I to II upgrades, Series II, & Series 2L

New Software Updates

To Be performed By:

Agilent Technologies Qualified Personnel or HP/Agilent Technologies Trained Customer

Situation:

Quarterly software releases have contained small enhancements & defect patches pertinent only to 5DX users. There are some new features in software release 6.2 that will affect servicing the 5DX system. These new features are described below:

- 1) A new menu item in the User Interface. This item features a quicker way to manually align all the FOVs on the C&A board. This feature eliminates the need to manually align each FOV on the C&A board. This feature can be used when upgrading from the old C&A board to the current C&A board, upgrading from Series I to Series II, and during calibration. The menu item is located at "Utilities>Board Alignment>Manual Alignment>Manually align all FOVs."
- 2) Microsoft's Service Pack 5 (SP5), which makes Windows NT 4.0 Y2K compliant. SP5 adversely affects DOS commands. We recommended that functions be executed through the user interface if they are in the user interface. One common command

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ADMINISTRATIVE INFORMATION

SERVICE NOTE CLASSIFICATION:

INFORMATION ONLY

AUTHOR: TS	ENTITY: 0980	ADDITIONAL INFORMATION:
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"msuitest" can be executed by selecting "Confirm and Adjust>Imaging>MSUITEST Utility." Another common command "xcalib" can be executed by selecting "Confirm and Adjust>Adjust>x-ray Scan Controller>Adjust."

- 3) Corrected configuration files. Configuration files that required manual changes during the manufacturing process or system upgrade process have been corrected. Examples include the Y move error in the xyz.cfg file and .RAD error in the FOVcal.dat file.
- 4) The solder "shaded by solder" graph will also be automatically displayed with all other solder graphs.
- 5) A semi-automated panel-flow direction change procedure, eliminating many of the manual steps. In order to use this new feature, the system must have all necessary hardware installed (2nd Board In Place (BIP) sensor), use the new (6.0) C&A panel and of course operate on software 6.2 and higher. The full procedure is documented in the Solution/Action section below.

Solution / Action:

To change the direction the panel flows through the system with 6.2 software, use the following procedure:

5DX Panel Flow-Through Direction Change Procedure

1. Remove all panels from the 5DX system.
2. At the DOS prompt type "setloadcfg x" where x refers to:
 - 0- Left-to-Right system
 - 1- Right-to-Left system
 - 2- Left-side pass back
 - 3- Right-side pass back
3. Enter the AutoUI and select "UtilitiesPanel Handling Reset Panel Handling".
4. Select "Utilities>Load Panel Program" and choose the "HP5DX_512, 400FOV" panel program. Press<Enter>Under the Utilities menu, select "Panel Handling>Automatic Panel Load," then press "Enter". Insert the C&A Panel into the 5DX system. Make sure you insert the C&A Panel in the proper direction marked on the panel.
5. Exit the AutoUI and at the DOS command prompt type "BIPSET". This program will automatically find and save the new BIP (Board In Place) sensor location and save that location in the correct file.
6. Exit the AutoUI and at the DOS command prompt type "GOTOCAL -FLIP". This program automatically changes the CAD coordinates of x-ray viewable CAL panel features.
7. At the DOS command prompt, type "GOTOCAL -SET". This program will step you through the process of fine tuning all the fiducials on the C&A panel.
8. Swap the SMEMA cables on the DIO (Digital Input/Output). There is a SMEMA connector cable below each outer barrier. Each of these cables connect to the DIO. Connect the panel-in cable to the SMEMA IN connector on the DIO. And connect the panel-out cable to the SMEMA OUT connector on the DIO.